

FIG. 1

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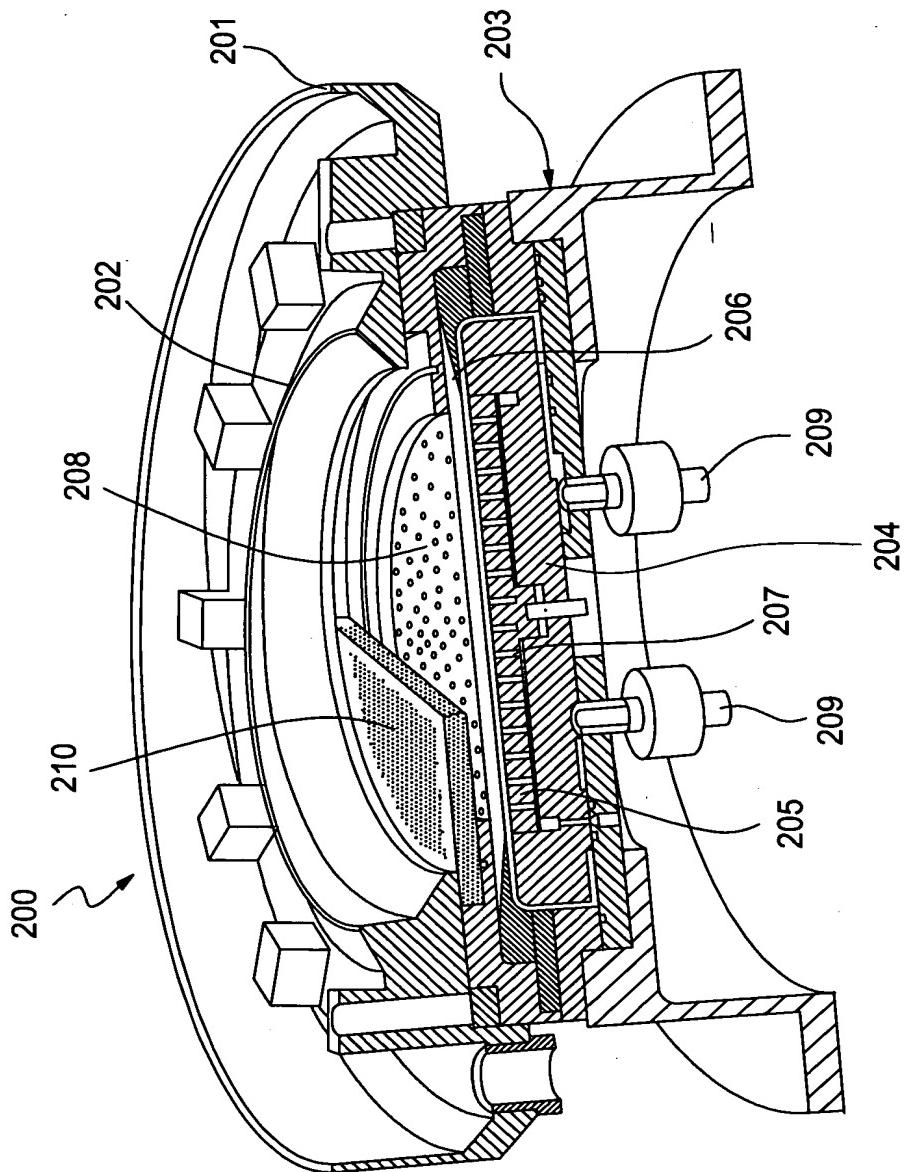


FIG. 2

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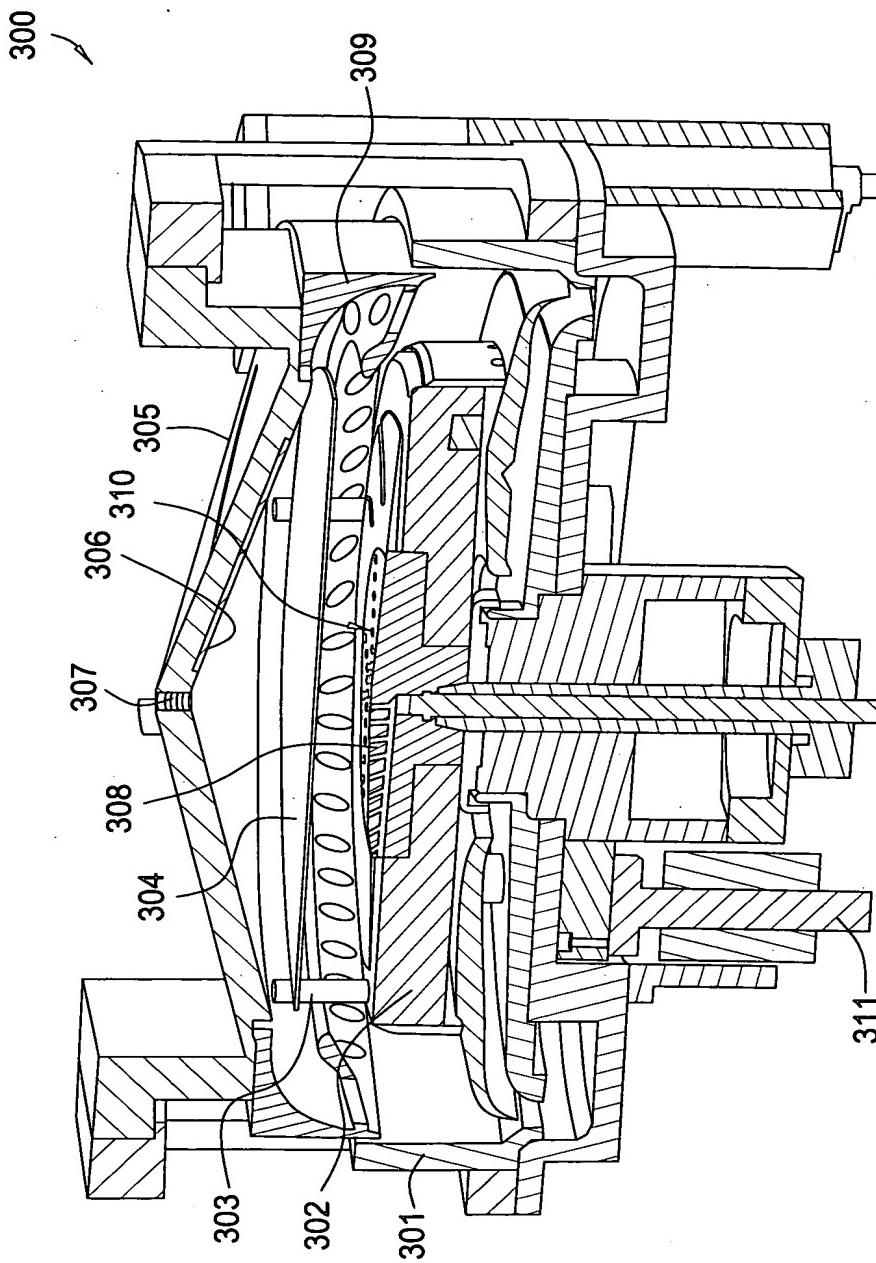


FIG. 3

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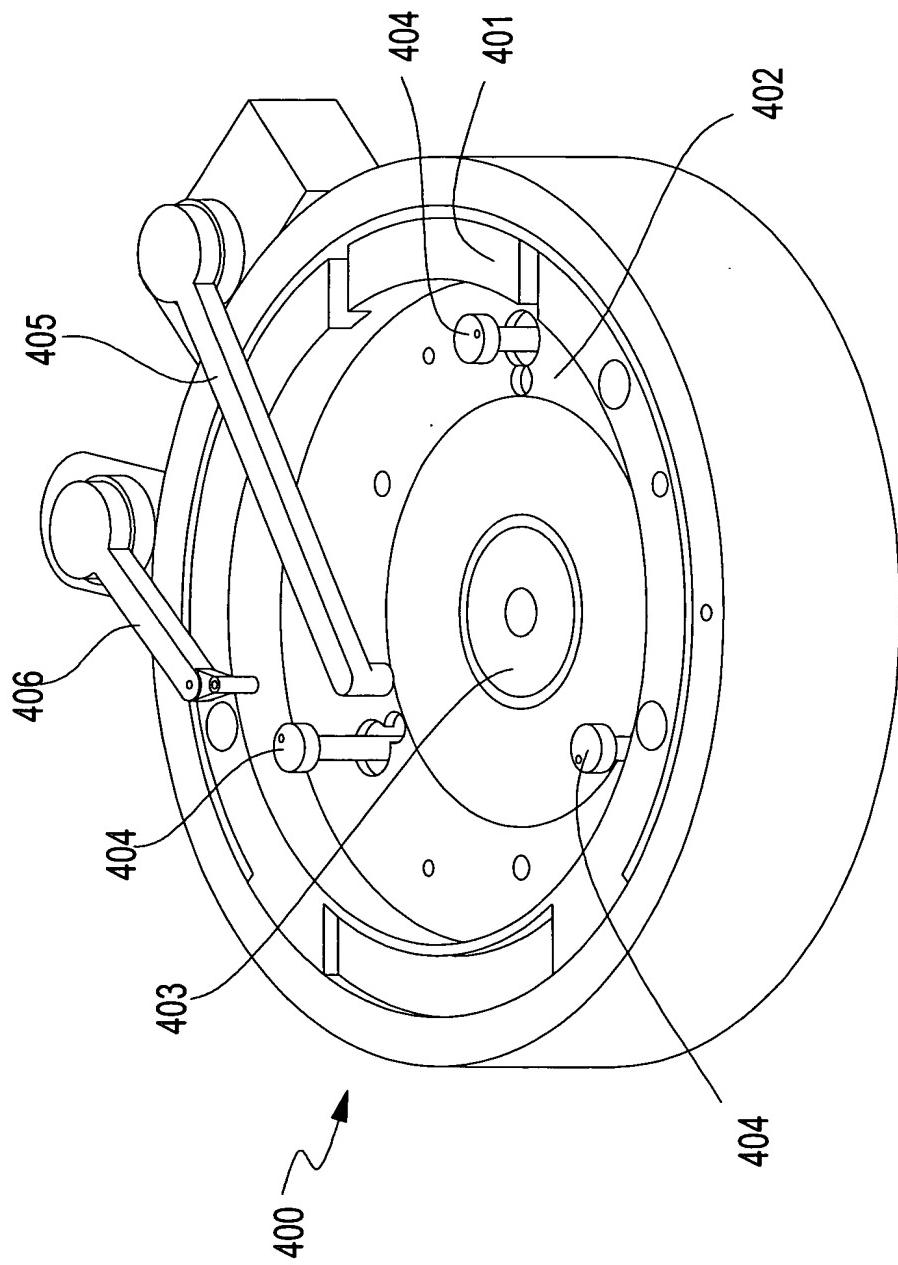


FIG. 4

ATTY DKT. No.: AMAT/7589/CMP/ECP/RKK
U.S. SERIAL No.: UNKNOWN CONF. No.: UNKNOWN
FILED: HEREWITH APPLICANT: APPLIED MATERIALS
TITLE: FORMATION OF PROTECTION LAYER BY DRIPPING DI ON
WAFER WITH HIGH ROTATION TO PREVENT STAIN FORMATION FROM
H2O2/H2SO4 CHEMICAL SPLASH
INVENTOR: BO ZHENG, ET AL.
EXPRESS MAIL No.: EV335470802US

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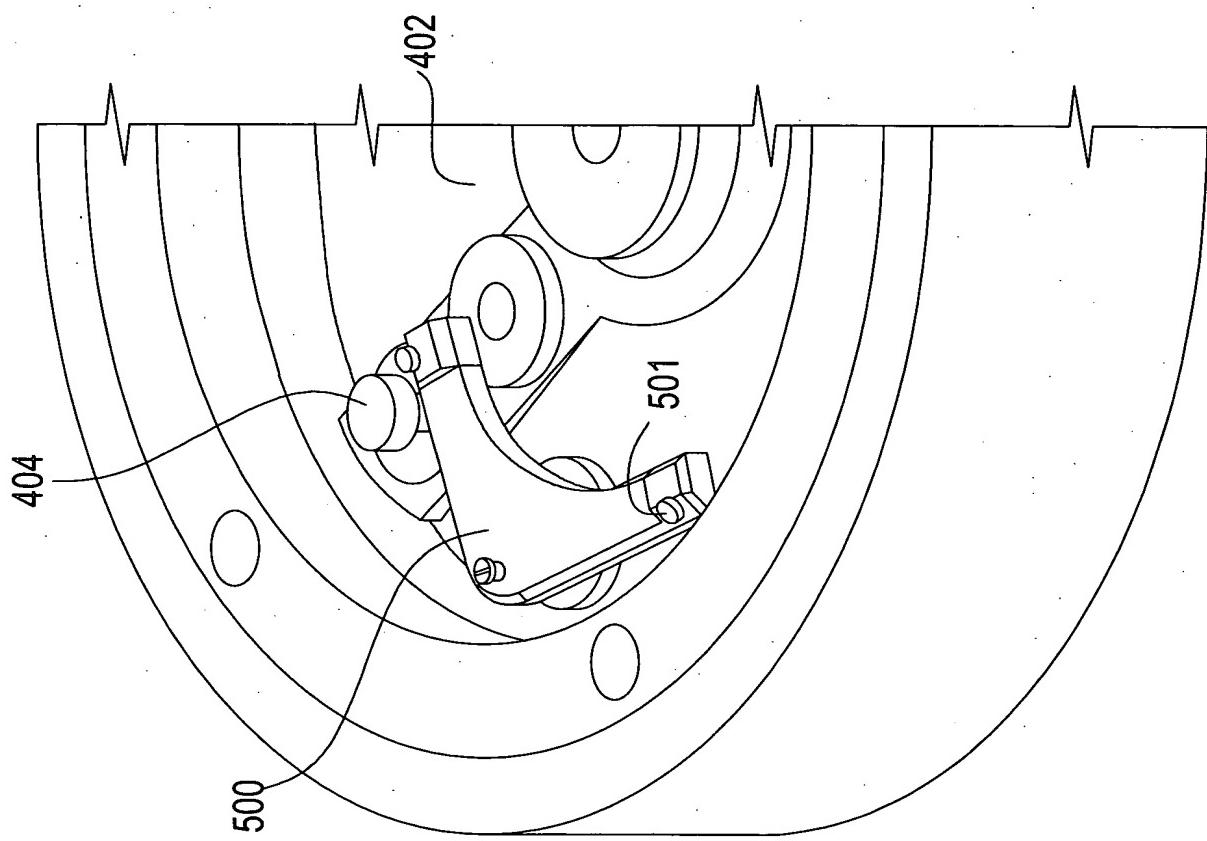


FIG. 5

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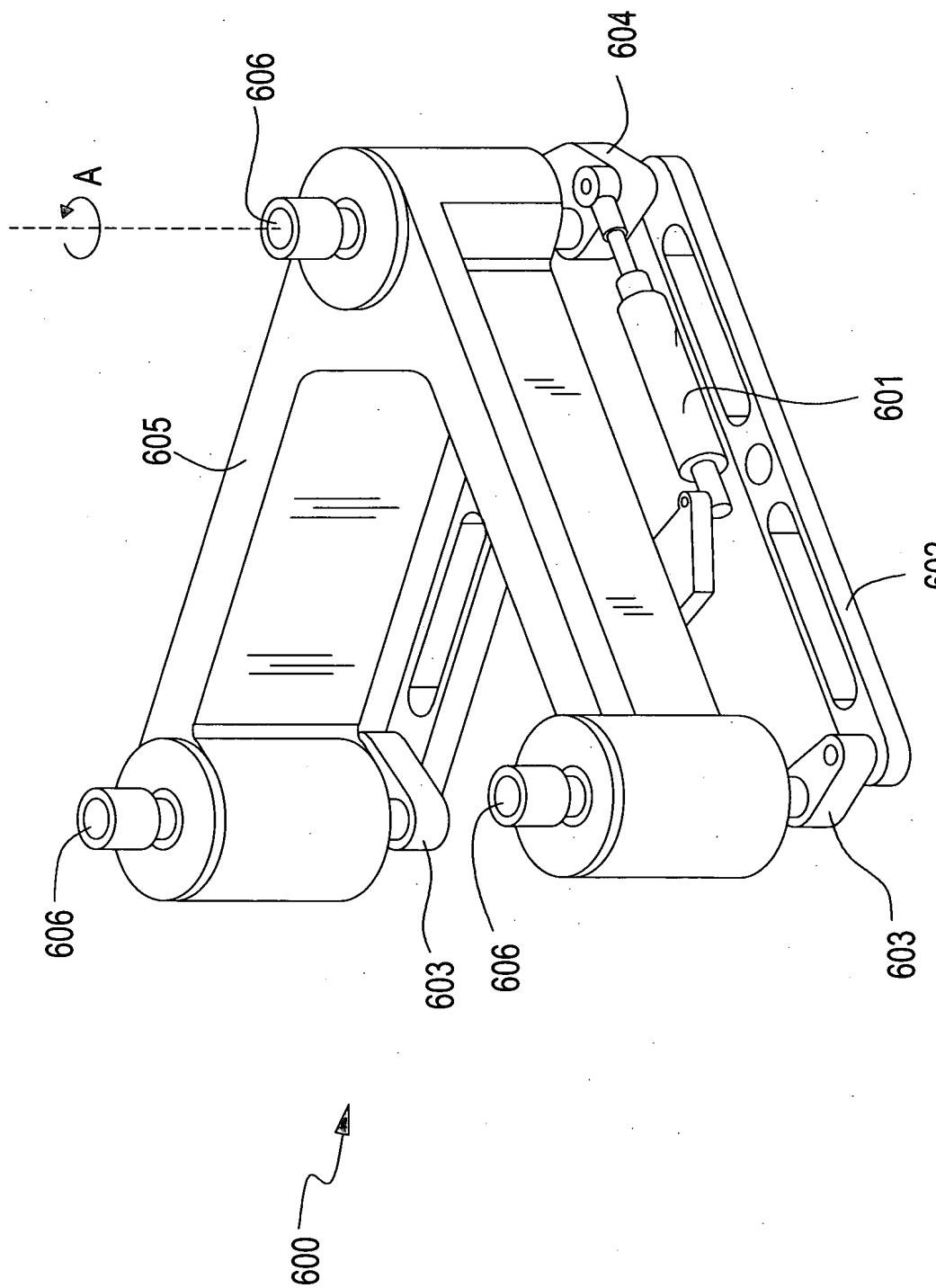


FIG. 6

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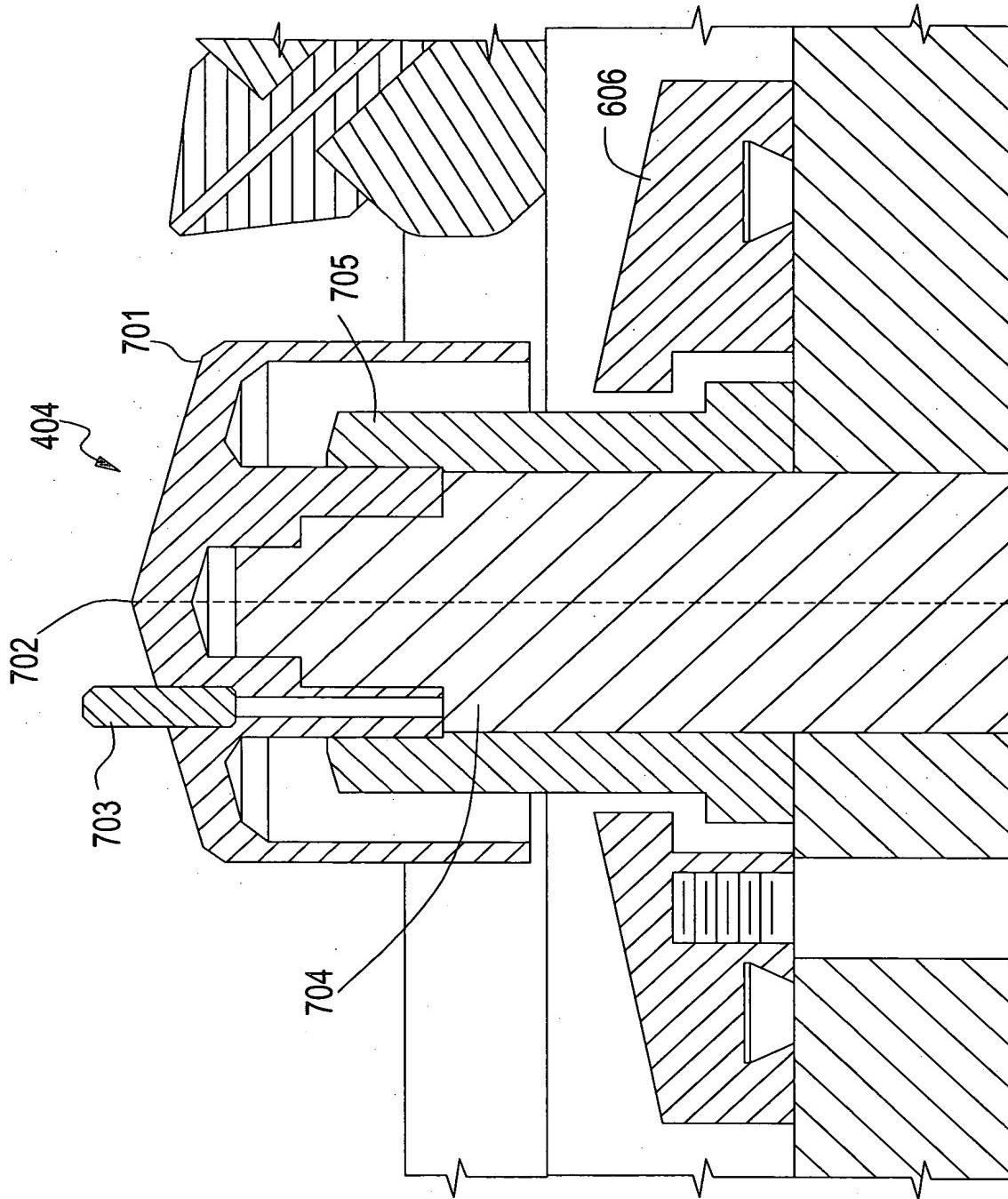


FIG. 7A

ATTY DKT. No.: AMAT/7589/CMP/ECP/RKK
U.S. SERIAL No.: UNKNOWN CONF. No.: UNKNOWN
FILED: HEREWITH APPLICANT: APPLIED MATERIALS
TITLE: FORMATION OF PROTECTION LAYER BY DRIPPING DI ON
WAFER WITH HIGH ROTATION TO PREVENT STAIN FORMATION FROM
H₂O₂/H₂SO₄ CHEMICAL SPLASH
INVENTOR: BO ZHENG, ET AL.
EXPRESS MAIL NO.: EV335470802US PAGE 8 OF 8

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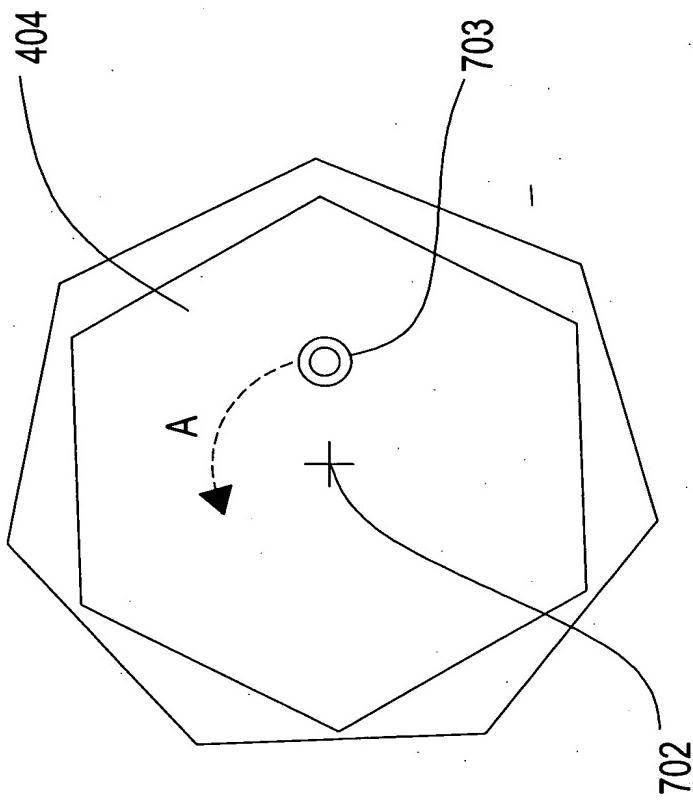


FIG. 7B